

ABSTRACT

TITLE OF INVENTION: MOLD RELEASE FILM, PROCESS FOR ITS PRODUCTION
AND PROCESS FOR PRODUCING SEMICONDUCTOR PACKAGE

5 To provide a mold release film which is not easily electrically charged or curled,
does not contaminate a mold, and has excellent mold followability, a process for its
production, and a process for producing a semiconductor package by using the mold
release film. A mold release film to be disposed on a surface of a mold which is to be in
contact with a curable resin, in a process for producing a semiconductor package by
10 disposing a semiconductor element in the mold, and sealing it with the curable resin to
form a resin sealed portion, comprising a first thermoplastic resin layer to be in contact
with the curable resin at the time of forming the resin sealed portion, a second
thermoplastic resin layer to be in contact with the mold at the time of forming the resin
sealed portion, and an interlayer disposed between the first thermoplastic resin layer
15 and the second thermoplastic resin layer, wherein the first thermoplastic resin layer and
the second thermoplastic resin layer have a storage elastic modulus at 180°C of from
10 to 300 MPa, respectively, the difference in storage elastic modulus at 25°C between
them is at most 1,200 MPa, and their thicknesses are from 12 to 50 μm , and
the interlayer includes a layer containing a polymeric antistatic agent.

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[Figure 1]